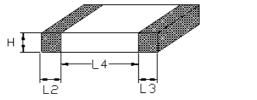


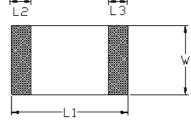
Multilayer Ceramic Chip Capacitor

Syfer Technology Ltd offers Multilayer Ceramic Chip Capacitors of the highest quality and reliability for a range of demanding applications. Manufactured using our "Wet Process", the range encompasses 10V to 12kV capability, with a variety of termination options including FlexiCap™, the worlds first commercially available flexible termination.

Part Number: 0805Y0500104KXTM01



Description: 0805 50V 100nF ±10% X7R (2R1)



Mechanical Specification		
Syfer Size Code	0805	
Length (L1) mm	2.0 ± 0.3	
Width (W) mm	1.25 ± 0.2	
Thickness (H) mm	1.3 Max.	
Termination Bands (L2,L3) mm	0.13 - 0.75	
Minimum Band Gap (L4) mm	0.2	
Termination Material	100% Matte Sn over Ni, FlexiCap™ base	
Solderability	IEC 60068-2-58	
RoHS Compliant to 2011/65/EC	Yes	
REACH Compliant	Yes	
Packaging	Taped and Reeled, 7 inch Reel	
General Electric Specifications		
Rated Voltage	50V	
Nominal Capacitance Value	100nF	

General Electric Specifications			
Rated Voltage	50V		
Nominal Capacitance Value	100nF		
Capacitance Tolerance	±10%		
Tangent of Loss Angle (Tan δ)	≤0.025		
Capacitance and Tan δ Test Conditions	1Vrms @ 1kHz		
Voltage Proof (Voltage applied for 5 secs max. @ 50mA max. charge current)	2.5 x Rated Voltage		
Min Insulation Resistance (IR)	10 GΩ		
Dielectric Classification	X7R (2R1)		
Rated Temperature Range	-55°C - +125°C		
Maximum Capacitance Change over Temperature Range	No DC Voltage	±15%	
	Rated DC Voltage	-	
Climatic Category (IEC)	55/125/56		
Ageing Characteristic	Less than 2% per time decade		

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Email: syfersales@knowles.com Web: http://www.syfer.com This datasheet is for a standard item and is confirmed valid on the date generated, the latest published data for this part may differ and is available at http://www.syfer.com or by contacting us at syfersales@knowles.com

The information contained on this drawing is confidential and may not be copied in whole or part in any form or disclosed to a third party without the consent of Syfer Technology Ltd. and any customer mentioned within this specification.

Date: 25 April 2016